

**ABRACON, LLC
ENGINEERING/PROCESS CHANGE NOTIFICATION FORM**

ABRACON ENGINEERING ORIGINATOR:

IMPLEMENTATION DATE: 7/29/2013

NOTIFICATION DATE:

9/5/2018

SCD/DRAWING AFFECTED:

[AISM-1210 Series](#)
[SMD Molded Wound Chip Inductor](#)

REV: E

NEW REV: F

EFFECTIVITY DATE: 7/29/2013

ECO# M751

REASON FOR CHANGE:

Product series underwent update.

DETAILS OF SPECIFICATION CHANGE:

Updates:

Revised all electrical specifications
 Changed storage temperature
 Changed package dimensions

Updated datasheet:

<https://abracon.com/Magnetics/new/AISM-1210.pdf>

APPLICATION INFORMATION

Safety	Non Safety	Application:
(Check one)		
	O	

DISPOSITION OF CURRENT STOCK

- Scrap
- Transfer to: _____
- Use as is
- Return to vendor

ABRACON INTERNAL APPROVAL:

APPROVAL (PRES) _____ DATE 9/5/2018 _____

GLOBAL QUOTING/PRICING MGR _____ DATE 9/5/2018 _____

ENGINEERING VP _____ DATE 9/5/2018 _____

PURCHASING MGR _____ DATE 9/5/2018 _____

SALES VP _____ DATE 9/5/2018 _____

QUALITY & PROCESS IMPROVEMENT MGR: _____ DATE 9/5/2018 _____

CUSTOMER APPROVAL (If Applicable)

ENGINEERING: NAME: _____ TITLE: _____ DATE: _____

BUYER/PURCHASING: NAME: _____ TITLE: _____ DATE: _____